



TECHNICAL DATA SHEET

CATEGORY:

ALLOY

NAME:

96.5Sn/3.5Ag & 96Sn/4Ag

FEATURES

- HIGH PURITY
- HIGH TEMPERATURE - 221°C

DESCRIPTION

96.5% Tin / 3.5% Silver, 96% Tin / 4% Silver, and other Tin / Silver Alloys are used for high temperature/high reliability interconnect applications. Tin/Silver Alloys typically are used in electronic assembly, die attach, thick film, and applications in which the use of lead is prohibitive. CASTIN, which contains copper, antimony, silver, and tin, has proven superior in the prevention of the tin intermetallics typically found in high temp thermocycling. Tin/silver alloys are available in bar, cored wire, solid wire, foil, preforms, powder, and no-clean, water soluble and rosin solder pastes. Tin/silver no-clean solder pastes pass all Bellcore and IPC specifications.

IMPURITY LEVELS TO IPC-JSTD-006 in Percent

Al: 0.005	Bi: 0.10	Fe: 0.02	Pb: 0.10
As: 0.03	Cd: 0.002	In: 0.10	Sb: 0.05
Au: 0.05	Cu: 0.08	Ni: 0.01	Zn: 0.003

HANDLING

Refer to the specific Material Safety Data Sheet and the handling section of the individual Technical Data Sheets for the chemistry type of LF218™ solder paste being used.

FLUX COMPATIBILITY

Tin/silver alloys are compatible with most electronic grade fluxes.

CLEANING

Refer to the flux manufacturer's data sheet for specific cleaning information.

TEMPERATURE REQUIREMENTS

APPLICATION	RECOMMENDED TEMPERATURE
REFLOW SOLDERING	PEAK TEMPERATURE 240° - 250°C (464° - 482°F)
WAVE SOLDER	POT TEMPERATURE OF 260°C (500°F)
HAND SOLDER - SOLDERING IRON	TIP TEMPERATURE OF 355° - 410°C (700° - 800°F)

SAFETY

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying **Material Safety Data Sheet** for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

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